

Guest Editorial

Special Issue on Nanowire Transistors: Modeling, Device Design, and Technology

THE RAPID development of integrated circuit technology is primarily due to MOSFET downscaling trends that have continued to the present day. However, silicon-based MOS technology is expected to face fundamental limits in the near future, and therefore, new types of nanoscale devices are being investigated aggressively. Recently, various semiconductor nanowire devices have drawn much attention because of their possible use in future electronics and optoelectronics applications. Continued MOSFET scaling has led to the study of nonplanar FET geometries that can provide better short channel control than conventional planar FETs. In particular, gate-all-around or surround gate FETs with a thin nanowire channel can provide superior electrostatic characteristics that will allow continued scaling beyond what is possible with planar technology.

Variability in these devices is also a topic of aggressive investigation. For smaller nanowire diameters, the inversion charge changes from surface inversion to bulk inversion due to quantum confinement. Variations in nanowire dimensions due to fabrication imperfections can lead to perturbations in the carrier potential and scattering that degrade the charge transport characteristics. Additionally, variations in nanowire diameters may lead to a variation in FET threshold voltage. Reducing variability is therefore a key challenge in making nanowire FETs a viable technology.

Among the different materials considered for growing nanowires, silicon has been studied extensively due to its compatibility with conventional Si CMOS technology. Si nanowires with diameters as small as one nanometer have been grown successfully. Ge nanowires are also of particular interest due to their higher carrier mobility. Nanowire-based transistors have also been demonstrated using a number of other materials, chief among these are ZnO, SnO, SiC, InP, GaN, other III-V compounds, and conducting polymers. Not only can nanowires be prepared from a diverse range of materials but also they can be integrated with very dissimilar materials. For example, Ge nanowires and even III-V nanowires have been grown on silicon substrates. Nanowires with a lattice constant different from that of the substrate can elastically accommodate the lattice mismatch and can be grown defect free. This is an opportunity that was not previously available to crystal growers. Similarly, nanowires with heterostructures along the main axis of the nanowire as well as in the radial direction have been demonstrated. Because of the diversity of materials available

for fabricating nanowire transistors, the breadth of potential applications is significant and includes chemical and biological sensing, high-performance electronic circuits on glass or plastic substrates, a variety of memory types, flexible electronics, displays, nanocomputers, and atomic-scale light-emitting diodes.

Quantum confinement effects make modeling of nanowire transistors a complex problem. While there are many studies in the literature on the modeling of nanowire transistors based on nonequilibrium Green function or Monte Carlo approaches, the physics related to the operation of nanowire transistors needs to be well articulated so that simple compact models, including ballistic transport and realistic subband parameters, can be developed for circuit design using SPICE-like simulators.

Devices based on nanowires can be fabricated using a “bottom-up” approach (such as CVD or liquid-vapor-phase growth and self-assembly) or a “top-down” approach (using photolithography and etching). Most bottom-up approaches are statistical by nature and are lacking the fidelity of top-down fabrication. Yet, their integration with traditional top-down fabrication is already taking place in applications such as nonvolatile memories and in the realization of ultralow- κ dielectrics for back end of line applications. Bottom-up approaches for making nanoscale devices circumvent some of the fabrication challenges and the high cost of equipment that are associated with established top-down CMOS processing. Acquiring and maintaining such big-ticket infrastructure which is prone to becoming obsolete at a rapid rate is out of bounds to most universities and even to many corporations. Therefore, there is a great need to focus on bottom-up fabrication methods for nanowire devices since they enable a wider range of academic institutions, laboratories, and corporations to participate and contribute to the growth of nanowire electronics.

Due to the rapid development taking place in the area of nanowires, there is an immediate need to bring the potential of nanowire devices to the notice of device designers and technologists working within the confines of Si CMOS technology. The primary goal of this special issue is, therefore, to compile advances in different aspects of nanowire-based devices including device physics and modeling, device design, characterization techniques, technology, and applications so that this special issue will not only be of great archival value but also attract new researchers into this area for further accelerating the application of nanowires in building cheaper and higher performance electronic systems.

This special issue of the IEEE TRANSACTIONS ON ELECTRON DEVICES and the IEEE TRANSACTIONS ON NANOTECHNOLOGY contains both invited papers surveying

recent developments and contributed papers reporting original results. The papers are divided between these two journals to reflect the scope of each of these journals. Many internationally renowned experts from across the world have contributed to this special issue, making it perhaps the first ever effort in putting together an invaluable collection of knowledge in the field of nanowire electronics.

The following papers will appear in the IEEE TRANSACTIONS ON NANOTECHNOLOGY:

- 1) *Real Time, Label Free Detection of Biological Entities Using Nanowire Based Field Effect Transistors*
- 2) *Chemical Sensors and Electronic Noses Based on One-Dimensional Metal Oxide Nanostructures*
- 3) *Characteristic Features of One-Dimensional Ballistic Transport in Nanowire MOSFETs*
- 4) *Highly Sensitive ZnO Nanowire Acetone Vapor Sensor with Au Adsorption*
- 5) *SPICE Modeling of Silicon Nanowire Field Effect Transistors for High-Speed Analog Integrated Circuits*
- 6) *Dual Nanowire Silicon MOSFET with Silicon Bridge and TaN Gate*
- 7) *Nanorods of LiF:Mg, Cu, P as Detectors for Mixed Field Radiations*
- 8) *Temperature Dependence of Carrier Transport of Silicon Nanowire Schottky Barrier Field Effect Transistor*
- 9) *Self Assembled Nanowire Arrays of Metal-Insulator-Semiconductor Diodes Exhibiting S-Type NonLinearity*
- 10) *Palladium Nanowires Assembly by Dielectrophoresis Investigated as Hydrogen Sensors*
- 11) *Enhanced Electrical Conductance of ZnO Nanowire FET by Non-destructive Surface Cleaning*
- 12) *Metal-Semiconductor Field Effect Transistors (MESFETs) Made From Individual GaN Nanowires*
- 13) *Band Effects on the Transport Characteristics of Ultra-Scaled SNW-FETs*
- 14) *Electrical Characteristics of Back-Gated Bottom-up Silicon Nanowire Field Effect Transistors*
- 15) *Hydrogen Ion Sensing Using Schottky Contacted Silicon Nanowire FETs*
- 16) *Bandstructure Effects in Silicon Nanowire Hole Transport*
- 17) *Single Palladium Nanowire Via Electrophoresis Deposition Used as Ultra Sensitive Hydrogen Sensor*
- 18) *Electrical Failure Analysis of Au Nanowires.*

Publishing a special issue is not an easy task due to the strict deadlines and the need for an efficient coordination among the guest editors, authors, and the reviewers. However, the Editor-in-Chief of the IEEE TRANSACTIONS ON ELECTRON DEVICES, Dr. Doug Verret played a pivotal role in bringing coherence to the diverging views and provided effective leadership in making sure this special issue became a reality. The initiative taken by the Editor-in-Chief of the IEEE TRANSACTIONS ON NANOTECHNOLOGY, Prof. Aristides Requicha in joining with the Electron Devices Society to bring out this special issue is deeply appreciated. Ms. Jo Ann Marsh of the Electron Devices Society Office received all the manuscripts and acted as an effective bridge between the guest

editors, reviewers, and the authors. She was always prompt and was a pleasure to work with. We would like to thank the reviewers who have worked hard to provide prompt reviews and to make sure that the accepted papers met the high standards that our readers are used to. Finally, this special issue would not have been possible without the dedicated effort of all the guest editors. We hope that the contents will be of great interest to not only beginners in this area but also to those who are active contributors to the growth and application of nanowire electronics.

M. JAGADESH KUMAR, *Guest Editor*
Indian Institute of Technology
New Delhi 110 016, India
(e-mail: mamidala@ieee.org)

MARK A. REED, *Guest Editor*
Yale University
New Haven, CT 06520-1942 USA
(e-mail: mark.reed@yale.edu)

GEHAN A. J. AMARATUNGA, *Guest Editor*
University of Cambridge
Cambridge CB2 1TN, U.K.
(e-mail: gajl@cam.ac.uk)

GUY M. COHEN, *Guest Editor*
IBM T. J. Watson Research Center
Yorktown Heights, NY 10598 USA
(e-mail: guycohen@us.ibm.com)

DAVID B. JANES, *Guest Editor*
Purdue University
West Lafayette, IN 47907 USA
(e-mail: janes@ecn.purdue.edu)

CHARLES M. LIEBER, *Guest Editor*
Harvard University
Cambridge, MA 02138 USA
(e-mail: cml@cmliris.harvard.edu)

M. MEYYAPPAN, *Guest Editor*
Center for Nanotechnology,
NASA Ames Research Center
Moffett Field, CA 94035 USA
(e-mail: mmeyyappan@mail.arc.nasa.gov)

LARS-ERIK WERNERSSON, *Guest Editor*
University of Lund
Lund 221 00, Sweden
(e-mail: Lars-Erik.wernersson@ftf.lth.se)

KANG L. WANG, *Guest Editor*
University of California
Los Angeles, CA 90095 USA
(e-mail: wang@ee.ucla.edu)

ROBERT S. CHAU, *Guest Editor*
Intel Corp
Santa Clara, CA 95054-1549 USA
(e-mail: robert.s.chau@intel.com)

THEODORE I. KAMINS, *Guest Editor*
Hewlett-Packard Laboratories
Bristol, BS34 8QZ, U.K.
(e-mail: kamins@hp.com)

MARK LUNDSTROM, *Guest Editor*
Purdue University
West Lafayette, IN 47907 USA
(e-mail: lundstro@purdue.edu)

BIN YU, *Guest Editor*
Center for Nanotechnology,
NASA Ames Research Center
Moffett Field, CA 94035 USA
(e-mail: byu@mail.arc.nasa.gov)

CHONGWU ZHOU, *Guest Editor*
University of Southern California
Los Angeles, CA 90089 USA
(e-mail: chongwuz@usc.edu)



M. Jagadesh Kumar (M'95–SM'99) was born in Mamidala, Andhra Pradesh, India. He received the M.S. and Ph.D. degrees in electrical engineering from the Indian Institute of Technology (IIT), Madras, India.

From 1991 to 1994, he performed postdoctoral research on the modeling and processing of high-speed bipolar transistors in the Department of Electrical and Computer Engineering, University of Waterloo, Waterloo, ON, Canada. While with the University of Waterloo, he also did research on amorphous-silicon TFTs. From July 1994 to December 1995, he was initially with the Department of Electronics and Electrical Communication Engineering, IIT, Kharagpur, India, and then joined the Department of Electrical Engineering, IIT, New Delhi, India, where he became an Associate Professor in July 1997 and a Full Professor in January 2005. He has authored three book chapters and more than 120 publications in refereed journals and conference proceedings. He is the Editor-in-Chief of *IETE Technical Review*. He also serves on the editorial board of the *Journal of Computational Electronics*, *Recent Patents on Nanotechnology*, *Recent Patents on Electrical Engineering*, *Journal of Low Power Electronics*, and *Journal of Nanoscience and Nanotechnology*.

His teaching has often been rated as outstanding by the Faculty Appraisal Committee of IIT Delhi. His research interests include nanoelectronic devices, modeling and simulation for nanoscale applications, integrated-circuit technology, and power semiconductor devices.

Dr. Kumar is a Fellow of the Indian National Academy of Engineering and the Institution of Electronics and Telecommunication Engineers (IETE) India. He is an IEEE Distinguished Lecturer of the IEEE Electron Devices Society (EDS). He is also a member of the EDS Publications Committee and EDS Educational Activities Committee. He is an Editor for the IEEE TRANSACTIONS ON ELECTRON DEVICES. He has extensively reviewed for different international journals. He was the recipient of the 29th IETE Ram Lal Wadhwa Gold Medal for his distinguished contribution in the field of semiconductor device design and modeling and the 2008 IBM Faculty Award. He was the first recipient of ISA-VSI TechnoMentor Award given by the India Semiconductor Association in recognition of a distinguished Indian academician or researcher for playing a significant role as a mentor and researcher.



Mark A. Reed (SM'97) received the B.S. degree (with honors) in physics, the M.S. degree in physics, and the Ph.D. degree in solid-state physics from Syracuse University, Syracuse, NY, in 1977, 1979, and 1983, respectively.

He joined Texas Instruments Incorporated as a Member of Technical Staff in the Ultrasmall Electronics Branch, where he cofounded the Nanoelectronics Research Program. In 1988, he was elected to Senior Member of Technical Staff. In 1990, he joined the faculty of Yale University, New Haven, CT, where he holds a joint appointment as Professor with the Departments of Electrical Engineering and Applied Physics, Harold Hodgkinson Chair of Engineering and Applied Science, and Associate Director of the Yale Institute for Nanoscience and Quantum Engineering. He has given 20 plenary and more than 280 invited talks. He is the author of more than 175 professional publications and six books. He is the holder of 25 U.S. and foreign patents. His research interests include the investigation of electronic transport in nanoscale and mesoscopic systems, heterojunction materials and devices, molecular-scale electronic transport, plasmonic transport in nanostructures, and chem/bio nanosensors.

Prof. Reed is a Fellow of the American Physical Society and a member of the Connecticut Academy of Science and Engineering. He is an Editor for the IEEE TRANSACTIONS ON ELECTRON DEVICES. He was the recipient of the Kilby Young Innovator Award (1994), the Fujitsu ISCS Quantum Device Award (2001), the Yale Science and Engineering Association Award for Advancement of Basic and Applied Science (2002), and the IEEE Pioneer Award in Nanotechnology (2007).



Gehan A. J. Amaratunga received the B.Sc. degree in electrical/electronic engineering from Cardiff University, Wales, U.K., in 1979 and the Ph.D. degree in electrical/electronic engineering from the University of Cambridge, Cambridge, U.K., in 1983.

He has held the 1966 Professorship in engineering with the University of Cambridge since 1998. He currently heads the Electronics, Power and Energy Conversion Group, one of four major research groups within the Electrical Engineering Division of the Cambridge Engineering Faculty. He has worked for 25 years on integrated and discrete electronic devices for power conversion, and on the science and technology of carbon-based electronics for 22 years. He has an active research program on the synthesis and electronic applications of carbon nanotubes and other nanoscale materials. His group has many “firsts” emanating from his research in carbon, including field emission from n-doped thin-film amorphous carbon and diamond, laboratory synthesis of carbon nanonions, tetrahedral amorphous carbon (“amorphous diamond”)-Si heterojunctions, deterministic growth of single isolated carbon nanotubes in devices, high-current nanotube field emitters, and the polymer-nanotube composite solar cells. He is also has research interest in nanomagnetic materials for spin transport devices. He currently sits on the steering committee of the Nokia-Cambridge University Strategic Collaboration on Nanoscience and Nanotechnology and is the head of the Nokia-CU Nanotechnology for Energy Programme. His group was among the first to demonstrate integration of logic-level electronics for signal processing and high-voltage power transistors in a single IC (chip). His current research is focused on integrated power conversion circuits. He is a Cofounder of CamSemi—which is commercializing a new generation of power and mixed-signal ICs for power management with venture capital investment. He is also a founder of Enecsys, a company formed with his research students to develop and market integrated electronics for grid connection of small-scale solar, wind, and fuel cell generators. Nanoinstruments, a company he founded with his colleagues to commercialize CNT synthesis equipment, was recently sold to Aixtron. He has previously held faculty positions at the Universities of Liverpool (Chair in Electrical Engineering), Cambridge, and Southampton. He has held the U.K. Royal Academy of Engineering Overseas Research Award at Stanford University, Stanford, CA, and been a Royal Society visitor at the School of Physics, University of Sydney, Sydney, N.S.W., Australia. He has published over 450 journal and conference papers.

Dr. Amaratunga was elected a Fellow of the Royal Academy of Engineering, in 2004. In 2007, he was awarded the Royal Academy of Engineering Silver Medal “for outstanding personal contributions to British engineering.”



Guy M. Cohen received the B.Sc. degree in electrical engineering from Technion—Israel Institute of Technology, Haifa, Israel, in 1988, the M.Sc. degree in physical electronics from Tel Aviv University, Tel Aviv, Israel, in 1993, and the Ph.D. degree in electrical engineering from Technion—Israel Institute of Technology in 1998. His Ph.D. research included the study of tunnel devices and FETs made with InP/InGaAsP and related alloys for analog applications.

In 1996, he was a Visiting Scholar with CNET, France-Telecom Laboratories, Bangneux, France, where he studied amphoteric carbon doping of InGaAsP layers matched to InP. Since 1998, he has been with the IBM T.J. Watson Research Center, Yorktown Heights, NY, where he has worked on topics such as self-aligned double-gate MOSFETs, silicide for thin SOI, compliant substrates, strained-silicon-on-silicon, and mixed-orientation substrates. He has authored more than 30 technical papers. He is the holder of 40 U.S. and international patents. His current research interests include the study of silicon nanowires for CMOS technology.



David B. Janes (S’86–M’89) received the B.A. degree in physics from Augustana College, Rock Island, IL, in 1980 and the B.S.E.E., M.S.E.E., and Ph.D. degrees from the University of Illinois at Urbana–Champaign, Urbana, in 1980, 1981, and 1989, respectively.

From 1981 to 1985, he worked as a Research Scientist with the Research Division of Raytheon Company, where he was engaged in research on microwave devices and integrated circuits. His doctoral research focused on the impact of electron traps on the microwave performance of GaAs-based signal processing devices (acoustic charge transport devices). Since 1989, he has been with Purdue University, West Lafayette, IN, where he is a Professor of Electrical and Computer Engineering. From 2001 to 2003, he was a Research Program Coordinator for the Birck Nanotechnology Center. From 2003 to 2007, he was a Technical Director of the Institute for Nanoelectronics and Computing, a NASA-supported center. His past research interests include experimental studies on mesoscopic devices and compound semiconductor microwave devices and characterization of novel semiconductor heterostructures, including structures incorporating

low-temperature-grown GaAs. His current research interests include the development of molecular electronic components, nanowire/nanotube transistors, and chemical sensors.



Charles M. Lieber received the B.A. degree (with honors) in chemistry from Franklin and Marshall College, Lancaster, PA, in 1981 and the Ph.D. degree in chemistry from Stanford University, Stanford, CA, in 1985.

From 1985 to 1987, he was a Postdoctoral Fellow with the California Institute of Technology, Pasadena. In 1987, he joined the faculty of chemistry at Columbia University, New York, NY, as an Assistant Professor. In 1991, he joined Harvard University, Cambridge, MA, as a Full Professor, and currently holds a joint appointment as the Mark Hyman Professor of chemistry in the Department of Chemistry and Chemical Biology and the School of Engineering and Applied Sciences. His research interests include the chemistry and physics of materials, with emphasis on the rational synthesis of new nanoscale materials and nanostructured solids; the development of methodologies for the hierarchical assembly of nanoscale materials into complex and functional systems; the investigation of fundamental electronic and optoelectronic properties of nanoscale materials; and the design and development of integrated nanoelectronics and nanoelectronic-

biological systems.

Prof. Lieber is an elected member of the National Academy of Sciences and the American Academy of Arts and Sciences, and a Fellow of the American Physical Society and the American Association for the Advancement of Science.



M. Meyyappan (A'85–M'89–SM'96–F'04) is currently the Chief Scientist for Exploration Technology at the Center for Nanotechnology, NASA Ames Research Center, Moffett Field, CA. His research interests include carbon nanotubes and inorganic nanowires and their applications in nanodevices, sensors, and instrumentation.

Dr. Meyyappan is a Fellow of the Electrochemical Society, American Vacuum Society, and the California Council of Science and Technology. He was the President of the IEEE's Nanotechnology Council during 2006–2007.



Lars-Erik Wernersson received the M.S. degree in engineering physics and the Ph.D. degree in solid-state physics from Lund University, Lund, Sweden, in 1993 and 1998, respectively.

During 2002–2003, he was a Visiting Associate Professor at the University of Notre Dame, Notre Dame, IN. Since 2005, he has been a Professor of nanoelectronics with Lund University. He has authored or coauthored more than 70 papers. His research interests include the design and fabrication of nanowire- and tunneling-based nanoelectronic devices and circuits with applications in low-power electronics and wireless communication.



Kang L. Wang (F'92) received the Ph.D. degree from the Massachusetts Institute of Technology, Cambridge, in 1970.

From 1970 to 1972, he was an Assistant Professor with the Massachusetts Institute of Technology. From 1972 to 1979, he was with the Corporate Research and Development Center, General Electric. In 1979, he was with the Electrical Engineering Department, University of California, Los Angeles (UCLA), where he served as the Chair of this department from 1993 to 1996. He was the Dean of Engineering from 2000 to 2002 with the Hong Kong University of Science and Technology, Kowloon, Hong Kong. He is the holder of the Raytheon Chair Professor of Physical Electronics with the Electrical Engineering Department, UCLA. He also currently serves as the Director of the Focus Center Research Program Center on Functional Engineered Nano Architectonics (FENA), which is an interdisciplinary research center that is funded by the Semiconductor Industry Association and the Department of Defense to address the need of information processing technology beyond scaled CMOS. FENA involves

15 universities across the nation. He was also named the Director of the Western Institute of Nanoelectronics, which is a coordinated multiproject research institute that is funded by the Nanoelectronics Research Initiative, Intel, and the State of California. The current ongoing projects with the University of California, Berkeley, Stanford University, University of California, Santa Barbara, and UCLA are aimed at spintronics for low-power applications. He was also the Founding Director of the Nanoelectronics Research Facility, UCLA (established in 1989), with the infrastructure to further research in nanotechnology. He was the inventor of the strained layer MOSFET, quantum SRAM cell, and band-aligned superlattices. He is the author or coauthor of more than 300 papers published in international journals and conference proceeding. His research activities include semiconductor nanodevices and nanotechnology; self-assembly growth of quantum structures and cooperative assembly of quantum-dot arrays Si-based molecular beam epitaxy, quantum structures and devices; nanoepitaxy of heterostructures; spintronic materials and devices; and SiGe MBE and quantum structures. He is the holder of 17 patents.

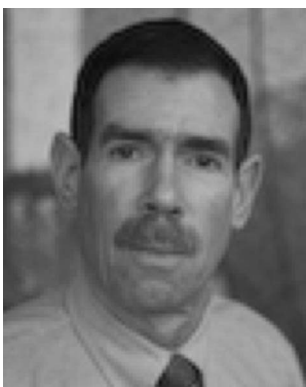
Dr. Wang serves on the editorial board of the *Encyclopedia of Nanoscience and Nanotechnology* (American Scientific Publishers), as a Senior Editor of the IEEE TRANSACTIONS ON NANOTECHNOLOGY, and as a Series Editor of *Nanoscience and Nanotechnology* (Artech House, Boston). He was a recipient of the following awards: the IBM Faculty Award; the Guggenheim Fellow Award; the TSMC Honor Lectureship Award; the Honoris Causa Award from the Politechnic University, Torino, Italy; the Semiconductor Research Corporation Inventor Awards; and the Technical Excellence Achievement Award from Semiconductor Research Corporation.



Robert S. Chau (F'05) received the B.S., M.S., and Ph.D. degrees from The Ohio State University, Columbus, all in electrical engineering.

He is currently an Intel Senior Fellow and the Director of Transistor Research and Nanotechnology, Intel Corporation, Hillsboro, OR. He is responsible for directing research and development in advanced transistors and gate dielectrics, process modules and technologies, and integrated processes for microprocessor applications. He is also responsible for leading research efforts in emerging nanotechnologies for future nanoelectronics applications. He is the holder of more than 75 U.S. patents.

Dr. Chau was a recipient of six Intel Achievement Awards and 13 Intel Logic Technology Development Division Recognition Awards. He was also recognized by IndustryWeek in 2003 as 1 of the 16 "R&D Stars" in the U.S. who "continue to push the boundaries of technical and scientific achievement."



Theodore I. Kamins (S'65–M'68–SM'79–F'91) received the B.S., M.S., and Ph.D. degrees from the University of California, Berkeley, all in electrical engineering.

He is currently a Principal Scientist with the Quantum Science Research Group, Hewlett-Packard Laboratories, Palo Alto, CA, where he has conducted research on numerous semiconductor material and device topics. He is also a Consulting Professor with the Electrical Engineering Department, Solid State and Photonics Laboratory, Stanford University, Stanford, CA. He has also worked on epitaxial and polycrystalline silicon at the Research and Development Laboratory, Fairchild Semiconductor. He is the author of *Polycrystalline Silicon for Integrated Circuits and Displays* (Kluwer, 1998) and a coauthor of *Device Electronics for Integrated Circuits* (Wiley, 2003). His current research interests include advanced nanostructured electronic materials and devices.

Dr. Kamins is a Fellow of the Electrochemical Society.



Mark Lundstrom (S'72–M'74–SM'80–F'94) received the B.E.E. and M.S.E.E. degrees from the University of Minnesota, Minneapolis, in 1973 and 1974, respectively, and the Ph.D. degree in electrical engineering from Purdue University, West Lafayette, IN, in 1980.

From 1974 to 1977, he was with Hewlett–Packard Corporation, Loveland, CO, on integrated circuit process development and manufacturing support. In 1980, he was with the School of Electrical Engineering, Purdue University, West Lafayette, where he is currently the Don and Carol Scifres Distinguished Professor of electrical and computer engineering and the Founding Director of the Network for Computational Nanotechnology. From 1989 to 1993, he served a Director of Purdue University's Optoelectronics Research Center and, from 1991 to 1994, as an Assistant Dean of Engineering. His research interests center on carrier transport in semiconductors and the physics of small electronic devices, particularly nanoscale transistors.

Dr. Lundstrom currently serves as an IEEE Electron Devices Society Distinguished Lecturer. He is a Fellow of the American Physical Society and of the American Association for the

Advancement of Science. In 1992, he received the Frederick Emmons Terman Award from the American Society for Engineering Education. With his colleague, S. Datta, he was awarded the 2002 IEEE Cleo Brunetti Award for their work on nanoscale electronic devices. In the same year, they shared the Semiconductor Research Corporation's Technical Excellence Award. In 2005, he received the Semiconductor Industry Association's University Researcher Award for his career contributions to the physics and simulation of semiconductor devices. Most recently, in 2006, he was the inaugural recipient of the IEEE Electron Devices Society's Education Award.



Bin Yu (A'92–SM'97–F'02) received the Ph.D. degree in electrical engineering from the University of California at Berkeley, Berkeley, where he was engaged in research on solid-state devices and thin-film SOI technology.

He led exploratory device research at Advanced Micro Devices, Inc., with the research focus on exploratory semiconductor device architectures and advanced technology for high-speed computing. His accomplishments include the world's first 10-nm double-gate transistor and the industry's first terahertz silicon transistor, among others. He is currently a Senior Research Scientist with the University-Affiliated Research Center/National Aeronautics and Space Administration, Ames Research Center, Moffett Field, CA. He is also a Consulting Professor of electrical engineering with Stanford University, Stanford, CA. He is the author or coauthor of more than 80 research papers, and has edited four books/book chapters. His current research interests include self-assembly of functional nanostructures to emerging nanodevice applications in information processing and storage.

Dr. Yu is a member of the IEEE Nanotechnology Council and Ex-Officio AdCom Member of the IEEE Electron Devices Society. He has served on technical committees, advisory committees, and invited guest panels of many international conferences and organizations, including the NNI/SRC Consultative Group and the International Roadmap for Semiconductors. He is an Editor of the IEEE ELECTRON DEVICE LETTERS, Associate Editor of the IEEE TRANSACTIONS ON NANOTECHNOLOGY, and Distinguished Lecturer of IEEE Electron Devices Society.



Chongwu Zhou received the B.S. degree from the University of Science and Technology of China, Hefei, China, in 1993 and the Ph.D. degree in electrical engineering from Yale University, New Haven, CT, in 1999.

He was a Postdoctoral Research Fellow with Stanford University, Stanford, CA, from November 1998 to June 2000. In September 2000, he joined the faculty at the University of Southern California, Los Angeles, where he is currently the Jack Munushian Associate Professor of Electrical Engineering. His research group has been working at the forefront of nanoscience and nanotechnology, including synthesis and applications of carbon nanotubes and nanowires, biosensing, and nanotherapy. He has authored more than 70 journal publications, and his work has been reported by *Science*, *Scientific American*, *Physics Today*, *MRS Bulletin*, *Materials Today*, the National Cancer Institute, and the Royal Society of Chemistry.

Dr. Zhou is currently an Associate Editor of the IEEE TRANSACTIONS ON NANOTECHNOLOGY. He was a recipient of a number of awards, including the NSF CAREER

Award, the NASA TGiR Award, the USC Junior Faculty Research Award, and the IEEE Nanotechnology Early Career Award.